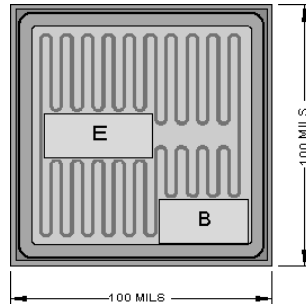


**Chip Type 2C6193**  
**Geometry 9700**  
**Polarity PNP**

**Generic Packaged Parts:**  
**2N6190, 2N6191, 2N6192,**  
**2N6193**



[Request Quotation](#)

Chip type **2C6193** by Semicoa Semiconductors provides performance similar to these devices.

**Part Numbers:**

2N6190, 2N6191, 2N6192, [2N6193](#)

**Product Summary:**

**APPLICATIONS:**

Designed for medium power switching and wide band applications.

**Features:** Medium power ratings  
 Radiation graphs available

Mechanical Specifications		
Metallization	Top	Al - 30.0 kÅ min.
	Backside	Au - 6.5 kÅ nom.
Bonding Pad Size	Emitter	12.0 mils x 40.0 mils
	Base	12.0 mils x 30.0 mils
Die Thickness	8 mils nominal	
Chip Area	100 mils x 100 mils	
Top Surface	Silox Passivated	

Electrical Characteristics				
$T_A = 25^\circ\text{C}$				
Parameter	Test conditions	Min	Max	Unit
$BV_{CEO}$	$I_C = 10.0\text{ mA}, I_B = 0$	100	---	V dc
$I_{CEO}$	$V_{CE} = 100\text{ V}, I_B = 0$	---	100	$\mu\text{A}$
$I_{CBO}$	$V_{CB} = 100\text{ V}, I_E = 0$	---	10	$\mu\text{A}$
$I_{EBO}$	$V_{EB} = 6.0\text{ V}, I_C = 0$	---	100	$\mu\text{A}$
$h_{FE}$	$I_C = 500\text{ mA}, V_{CE} = 2.0\text{ V}$	60	---	---

*Due to limitations of probe testing, only dc parameters are tested. This must be done with pulse width less than 300  $\mu\text{s}$ , duty cycle less than 2%.*